

INVENTORSHIP DECLARATION BY JOINT INVENTORS

I HEREBY DECLARE THAT:

My residence, mailing address, and citizenship are stated next to my name in PART A hereof.

I believe I am the original, first, and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

PACKAGED MICROELECTRONIC DEVICES AND
METHODS OF PACKAGING MICROELECTRONIC DEVICES

the specification of which:

- is attached hereto.
- was filed on _____ as Application Serial No. _____ and was amended on _____ (if applicable).

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 CFR §1.56, including, for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim priority benefits under 35 USC §119(a)-(d) or (f), §172, or §365(a)-(b) of any foreign or international application(s) for patent or inventor's certificate listed in PART B hereof and have also identified in PART B hereof any such foreign or international application having a filing date before that of the application of which priority is claimed.

I hereby declare that all statements made herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. I understand that the execution of this document does not in itself establish an attorney-client relationship between the undersigned and Perkins Coie LLP, or any of its attorneys.

See pages 2-3 attached, signed, and made a part hereof.

INVENTORSHIP DECLARATION BY JOINT INVENTORS

PART A: INVENTOR INFORMATION AND SIGNATURE

Full name of FIRST inventor: Suan Jeung Boon

Citizenship: Singaporean Mailing Address: 271-A Jln Kayu
Singapore 799499

Residence (if different): N/A

Inventor's Signature:  Date: 11 Aug 2003

Full name of SECOND inventor: Yong Poo Chia

Citizenship: Singaporean Mailing Address: Blk 37 #10-03 Bangkit Road
Singapore 679976

Residence (if different): N.A.

Inventor's Signature:  Date: 11 Aug 2003

Full name of THIRD inventor: Min Yu Chan

Citizenship: Singaporean Mailing Address: Blk 10F Braddell Hill #04-21
Singapore 2057

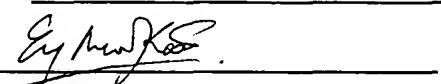
Residence (if different): N.A.

Inventor's Signature:  Date: 11 Aug 2003

Full name of FOURTH inventor: Meow Koon Eng

Citizenship: Singaporean Mailing Address: Blk 249 Pasir Ris Street 21, #02-125
Singapore 510249

Residence (if different): N.A.

Inventor's Signature:  Date: 11 Aug 2003

Full name of FIFTH inventor: Siu Waf Low

Citizenship: Malaysian Mailing Address: 30, Lengkok Angsa
Singapore 239282

Residence (if different): N. A.

Inventor's Signature: KW Siu Waf Date: 11-AUG-2003

Full name of SIXTH inventor: Swee Kwang Chua

Citizenship: Singaporean Mailing Address: Blk 690, Hougang Street 61, #06-264
Singapore 530690

Residence (if different): NA

Inventor's Signature: SK Date: 11-Aug '2003

INVENTORSHIP DECLARATION BY JOINT INVENTORS

**PART B: CLAIM TO PRIORITY OF FOREIGN APPLICATION(S) UNDER
35 U.S.C. §119(a)-(d) and (f), §172, or §365(a)-(b)**

Country	App. No.	Filing Date	Priority Not Claimed
Singapore	200303053-3	May 30, 2003	<input type="checkbox"/>
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